

CLAIMS

What is claimed is:

1. A method of attaching a semiconductor die to a lead frame comprising:
providing a source of snap curable adhesive;
providing a source of lead frames, each lead frame having an attaching surface;
providing a source of semiconductor die, each semiconductor die having an active surface;
applying said snap curable adhesive to a portions of one of the lead frames; and
contacting said active surface of one of the semiconductor die with said portions of one of
the lead frames having said snap curable adhesive thereon.

2. The method of claim 1, further including the step of:
heating one of said semiconductor die.

3. The method of claim 1, wherein said snap curable adhesive includes a snap
curable epoxy having a cure time of about one second.

4. The method of claim 1, wherein said snap curable adhesive includes an
adhesive having a cure time of substantially one minute or less.

5. The method of claim 1, wherein said snap curable adhesive is applied to the
portions of said one of the lead frames using a roller.

6. A method of attaching a semiconductor die to a lead frame comprising:
providing a source of snap curable adhesive;
providing a source of lead frames, each lead frame having an attaching surface;
providing a source of semiconductor die, each semiconductor die having an active surface;
applying said snap curable adhesive to a portions of the active surface of one of said
semiconductor die; and
contacting said curable adhesive with portions of one of said lead frames.

7. The method of claim 6, wherein said snap curable adhesive includes an adhesive having a curing time of about one second or less.

5 8. The method of claim 6, wherein said snap curable adhesive is applied to said active surface of one of said semiconductor devices in a predetermined pattern.

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